

Title (en)
Polyamide resin composition

Title (de)
Polyamid Harzzusammensetzung

Title (fr)
Composition de résine polyamide

Publication
EP 0940444 B1 20040929 (EN)

Application
EP 99104242 A 19990303

Priority
JP 5505498 A 19980306

Abstract (en)
[origin: EP0940444A2] A polyamide resin composition comprising 100 parts by weight of a polyamide resin and 0.005 to 1.0 part by weight of at least one compound selected from the group consisting of a metal salt of a fatty acid, a diamide compound and a diester compound. The polyamide resin is obtained by solid phase-polymerizing a polyamide resin prepared by melt-polymerizing a diamine component containing 70 mol% or more of metaxylenediamine and a dicarboxylic acid component containing 70 mol% or more of adipic acid, and preferably has a relative viscosity of 2.3 to 4.2 when measured at 25 DEG C using a solution of 1g polyamide resin in 100ml of 96% sulfuric acid. By adding at least one compound selected from the group consisting of the specific metal salt of fatty acid, the diamide compound and the diester compound to a solid phase-polymerized polyamide resin, shaped articles such as films, sheets and hollow containers made of the solid phase-polymerized polyamide are improved in the resistance to whitening during storage under a high humid condition, upon contacting with water or boiling water, or upon heating to a glass transition temperature or higher.

IPC 1-7
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IPC 8 full level
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Cited by
AU2012216788B2; EP1029883A1; AU758289B2; CN107022189A; EP2532712A1; EP2025718A4; US6303741B1; WO03035732A1; US8273431B2; US8940379B2; EP2554887B1

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